**MH88632** 

April 1995



**Central Office Interface Circuit** 

**Preliminary Information** 

#### Features

- Loop start and ground start capabilities
- Transformerless 2-4 wire conversion
- Programmable transmit/receive gain with 0dB defaults
- Programmable input impedance with 600Ω and 900Ω defaults
- Programmable network balance with 600Ω, 900Ω, and AT&T compromise default
- One loop start & two ground start relay drivers
- Line state detection outputs
- Forward loop, reverse loop, ring ground, tip ground, ringing voltage
- +5V operation
- On-hook audio reception (to accommodate ANI)

#### **Applications**

Interface to Central Office for:

- PBX
- Key Telephone System
- Channel bank
- Voice Mail
- Terminal Equipment
- Digital Loop Carrier

**Ordering Information** 

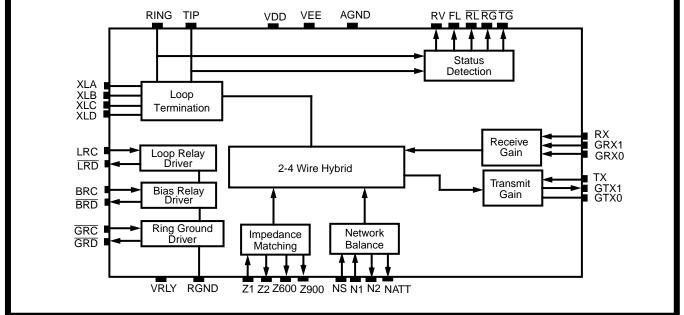
**ISSUE 5** 

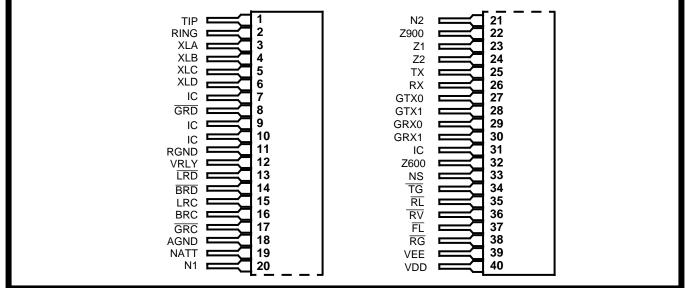
MH88632 40 Pin SIL Package

0°C to 70°C

#### Description

The Mitel MH88632 Central Office Trunk Interface circuit provides a complete audio and signalling link between audio switching equipment and a central office. The functions provided by the MH88632 include 2-4 Wire Hybrid conversion, programmable transmit and receive gains, programmable line impedance and programmable network balance. The device is fabricated using thick film hybrid technology which incorporates various technologies for optimum circuit design and very high reliability.





#### Figure 2 - Pin Connections

### **Pin Description**

Pin #	Name	Description					
1	TIP	Tip Lead. Connects to the "Tip" or "Ring" lead of Central Office.					
2	RING	Ring Lead. Connects to the "Ring" or "Tip" lead of the Central Office.					
3	XLA	Loop Relay Contact A. Connects to XLB through the loop relay (K1) contacts when the relay is activated. Activates internal active termination circuitry.					
4	XLB	Loop Relay Contact B. See XLA for description.					
5	XLC	<b>Loop Relay Contact C.</b> Connects to XLD through the loop relay (K1) contacts when the relay is activated. Activates internal active termination circuitry.					
6	XLD	Loop Relay Contact D. See XLC for description					
7	IC	Internal Connection. This pin is internally connected and must be left open.					
8	GRD	<b>Ground Relay Lead Relay Drive (Output).</b> Connects to the Ground Ring Lead Relay Coil, used for Ground Start applications. A logic low activates the relay. An internal clamp diode from VRLY to GND is provided.					
9	IC	Internal Connection. This pin is internally connected and must be left open.					
10	IC	Internal Connection. This pin is internally connected and must be left open.					
11	RGND	Relay Ground. Return path for relay supply voltage.					
12	VRLY	<b>Relay Positive Supply Voltage.</b> Normally +5V. Connects to the relay coil and the relay supply voltage					
13	LRD	<b>Loop Relay Drive (Output).</b> Connects to the Bias Relay coil. A logic low activates the relay. An internal clamp diode from VRLY to LRD is provided.					
14	BRD	<b>Bias Relay Drive (Output).</b> Connects to the Bias Relay coil, used for Ground start applications only. A logic low activates the relay. An internal clamp diode from VRLY to BRD is provided.					
15	LRC	<b>Loop Relay Control (Input).</b> A logic high activates the Loop Relay Drive output (LRD). The Loop Relay activates internal circuitry which provides a DC termination across Tip and Ring. Used for line seizure and dial pulsing.					

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# Pin Description (Continued)

Pin #	Name	Description						
16	BRC	<b>Bias Relay Control (Input).</b> A logic high activates the Loop Relay Drive output (BRD), used for Ground start applications only. This input should be connected to logic high when not used.						
17	GRC	<b>Ground Ring Lead Relay Control (Input).</b> A logic low activates the Ground Ring Lead Relay Drive output (GRD), used for Ground Start applications only. This input should be connected to logic high when not used.						
18	AGND	nalog Ground. 4-Wire ground. Normally connected to System Ground.						
19	NATT	<b>Network Balance AT+T Node.</b> Connects to N1 for a network balance impedance of AT compromise $(350\Omega + 1k\Omega // 210nF)$ ; the device's input impedance must be set to 600 $\Omega$ . This node is active only when NS is at logic high. This node should be left open circuit what used.						
20	N1	<b>letwork Balance Node 1 (Input).</b> 0.1 times the impedance between pins N1 and N2 munatch the device's input impedance, while 0.1 times the impedance between pins N1 an GND is the device's network balance impedance. This node is active only when NS is a bogic high. This node may be terminated when not used (i.e., NS at logic low).						
21	N2	Network Balance Node 2 (Output). See N1 for description.						
22	Z900	<b>Line Impedance 900</b> $\Omega$ <b>Node.</b> Connects to Z1 for a line impedance of 900 $\Omega$ . This node should be left open circuit when not used.						
23	Z1	<b>Line Impedance Node 1 (Input)</b> . 0.1 times the times the impedance between pins Z1 and Z2 is the device's line impedance. This node must always be connected.						
24	Z2	<b>Line Impedance Node 2 (Output).</b> 0.1 times the times the impedance between pins Z1 and Z2 is the device's line impedance. This node should be left open circuit when not used.						
25	ТХ	Transmit (output). 4-Wire ground (AGND) referenced audio output.						
26	RX	Receive (Input). 4-Wire ground (AGND) referenced audio input.						
27	GTX0	Transmit Gain Node 0. Connects to GTX1 for 0dB transmit gain.						
28	GTX1	Transmit Gain Node 1. Connects to a resistor to AGND for transmit gain adjustment.						
29	GRX0	Receive Gain Node 0. Connects to GRX1 for 0dB gain.						
30	GRX1	Receive Gain Node 1. Connects to a resistor to AGND for receive gain adjustment.						
31	IC	Internal Connection. This pin is internally connected and must be left open.						
32	Z600	<b>Line Impedance 600</b> $\Omega$ <b>Node (Output).</b> Connects to Z1 for a line impedance of 600 $\Omega$ . This pin should be left open circuit when not used.						
33	NS	<b>Network Balance Setting (Input.</b> The logic level at NS selects the network balance impedance. A logic 0 enables an internal balance equivalent to the input impedance (Zin). While a logic 1 enables an external balance 0.1 times the impedance between pins N1 and AGND balanced to 0.1 times the impedance between pins N1 and N2. The impedance between N1 and N2 must be equivalent to 10 times the input impedance (Zin).						
34	TG	<b>Tip Lead Ground Detect (Output).</b> A logic low output indicates that the Tip lead is at ground (AGND) potential.						
35	RL	<b>Ring Loop Detect (Output).</b> In the on-hook state, a logic low output indicates that reverse loop battery is present. In the off-hook state, a logic low output indicates that reverse loop current is present. Reverse loop refers to the Tip lead negative with respect to the Ring lead.						
36	RV	<b>Ring Voltage Detect (Output).</b> A logic low indicates that ringing voltage is across the Tip and Ring leads. Note that this output toggles at the ringing cadence and not at the ringing frequency.						

Pin #	Name	Description
37	FL	<b>Forward Loop Detect (Output).</b> In the on hook state, a logic low output indicates that forward loop battery is present. In the off-hook state, a logic low output indicates that forward loop current is present. Forward loop refers to the Ring Lead negative with respect to the Tip lead.
38	RG	<b>Ring Lead Ground Detect (Output).</b> A logic low indicates that the Ring lead is at ground (AGND) potential.
39	VEE	Negative Supply Voltage5V dc.
40	VDD	Positive Supply Voltage. +5V dc.

### Pin Description (Continued)

#### **Functional Description**

The MH88632 is a COIC (Central Office Interface Circuit) used to interface to Central Office 2-Wire Analog Trunks. The COIC provides both Loop start and Ground start interface capabilities.

### Approvals

FCC part 68, DOC CS-03, UL 1459, CAN/CSA 22.2 No.225-M90 are all system (i.e., connectors, power supply, cabinet, etc.) requirements. Since the MH88632 is a component and not a system, it cannot be approved as a stand alone part by these standards bodies. However, when installed into a properly designed system, the MH88632 has been designed to meet the CO Trunk Interface requirements of FCC, DOC, UL and CSA, and thus enabling the complete system to be approved by these standards bodies.

To meet the regulatory high voltage requirements, an external protection circuit is required. The protection circuit shown in Figure 9 is matched to the MH88632 and ensures than they meet the high voltage requirements of FCC, DOC, CSA and UL when installed in a properly designed system.

Products are designed in accordance with meeting the above requirements; however, full conformance to these standards is dependent upon the application in which the hybrid is being used, and therefore, approvals are the responsibility of the customer and Mitel will not have tested the product to meet the above standards.

# **DC Loop Termination**

The DC loop termination circuitry provides the loop with an active Dc load termination when a logic low is applied to the LRC (Loop Start Relay Control) input. the termination is similar to a DC resistance between  $200\Omega$  and  $275\Omega$ . An external relay is used to activate internal circuitry which switches the termination in and out of the loop. This is used for both seizing the line as well as generating dial pulses.

#### **Supervision Features**

The supervision circuitry provides the signalling status outputs. The system controlling the COIC, monitors these logic outputs. The supervision circuitry is capable of detecting ringing voltage, both forward and reverse loop battery and loop current, and both grounded tip lead and grounded ring lead.

# a) Supervision Features RV (Ring Voltage Detect Output)

The  $\overline{\text{RV}}$  (Ringing Voltage Detect) output provides a logic low when ringing voltage is detected. This detector includes a ringing filter which ensures that the output toggles at the ringing cadence and not at the ringing frequency. Typically, this output goes low 50ms after ringing voltage is applied and remains low for 50ms after ringing voltage is removed.

#### b) Supervision Features FL & RL (Forward Loop and Reverse Loop Detect Output).

The  $\overline{FL}$  (Forward Loop Detect) output provides a logic low when either forward loop battery or forward loop current is detected (ring lead voltage negative with respect to ring lead). The  $\overline{RL}$  (Reverse Loop Detect) output provides a logic low when either reverse loop battery or reverse loop current is detected (tip lead voltage negative with respect to ring lead).

See Table 5 for Loop Battery and Current Status Outputs.

#### c) Supervision Features TG & RG (Tip Ground and Ring Ground Detect Output)

The  $\overline{TG}$  (Tip Lead Ground Detect) output provides a logic low when the tip lead is at ground (AGND) potential. The  $\overline{RG}$  (Ring Lead Ground Detect) output provides a logic low when the Ring lead is at ground (AGND) potential.

See Table 6 for Loop Ground Status Outputs.

#### **Ground Start Signalling Features**

For Ground Start signalling, relay K2 and resistors R1 and R2, and relay K3 and resistor R3 are required (See Figure 8). Activation of K2 is controlled by the logic signal at the BRC (Bias Relay Control) input while activation of K3 is controlled by the logic signal at the GRC (Ground Relay Control) input.

K2 is used to engage the bias resistors while K3 is used to ground the right lead; this is used in ground start applications for signalling to the central office.

#### Typical Ground Start Signalling Protocol

Refer to Figure 8 for Typical LS-GS Application Circuit.

In the idle state, the system (e.g., PBX control card) provides a logic high to the BRC input. This activates the COIC's second internal relay driver which activates relay K2. Both contacts of relay K2 close, which connect the -48VDC supply to Tip (tip lead) and Ring (ring lead) through bias resistors R1 and R2.

Depending on which Ground Start protocol is used, initiating a Ground start call to the central office can be performed by the following sequence of events.

The system provides a logic low to the  $\overline{GRC}$  input. this activates the COIC's third internal relay driver which activates relay K3. The contacts of relay K3 close, which connects the ring lead to ground through a current limiting resistor R3.

The Central Office reconizes the ring ground condition and responds by grounding the tip lead.

The COIC senses the grounded Tip and switched the  $\overline{TG}$  (Tip Lead Ground Detect) output to a logic low.

The system then applies a logic high to the LRC (Loop Relay Control) input. This activates the COIC's first internal relay driver which activates relay K1. Both contacts the relay K1 close, which activates the COIC's internal circuitry resulting in an active line termination across Tip and Ring. The system then provides a logic low to the BRC input. This deactivates the COIC's second internal relay driver which deactivates K2. Both contacts of relay K2 open, which disconnect the bias from Tip and Ring. The system then provides a logic high to the GRC input. This deactivates the COIC's third internal relay driver which deactivates the COIC's third internal relay driver which deactivates the COIC's third internal relay driver which deactivates relay K3. The contact of relay K3 opens. which disconnects the grounded ring lead. The voice link is now established.

Receiving a Ground Start call from central office is performed similarly. The central office can signal the COIC by either grounding the tip lead or by grounding the ring lead.

#### Hybrid

The 2-4 Wire Hybrid circuit separates the balanced full duplex signal at Tip and Ring of the telephone line into receive and transmit ground referenced signals at Rx (Receive) and TX (Transmit) of the COIC. The hybrid also prevents the input signal at RX from appearing at TX. The degree to which the Hybrid minimises the contribution of the RX signal at the TX output is specified as transhybrid loss. For maximizing transhybrid loss, see the **Network Balance section.** 

The 4-Wire side can be interfaced to a filter/codec such as the Mitel MT896X, for use in digital voice switched systems.

#### Line Impedance

The MH88632's Tip-Ring impedance ( $Z_{in}$ ) can be set to 600 $\Omega$ , 900 $\Omega$  or to a user selectable value. Thus, Zin can be set to any international requirements. The connection to Z1 determines the input impedance. With Z1 connected to Z600, the line impedance is set to 600 $\Omega$ . With Z1 connected to Z900, the line impedance is set to 900 $\Omega$ . A user defined impedance can be selected which is 0.1 times the impedance between Z1 and Z2. For example, with 2200 $\Omega$  in series with 11.5nF in parallel with 8200 $\Omega$ , all between Z1 and Z2, the devices line impedance will be 220 $\Omega$  in series with 115nF in parallel with 820 $\Omega$ . See Table 3 and Figures 4 & 5.

# Stability

The part will be stable with an AC load over the range 0.5  $Z_{in}$  <Load < 2 x  $Z_{in}$ .

The range of loads that can be simulated by the MH88632 is extensive including those which are purely resistive and complex in nature. For loads with a low or zero series resistance additional measures need to be taken to maintain stability which involves simulating with a larger series resistance and adjusting other components accordingly.

#### Examples:

**Sweden**: Load is 900 $\Omega$  in a parallel with 30nF. This is synthesised on the MH88632 by  $1.5k\Omega$  in series with a parallel combination of 3nF and 7.4k $\Omega$ .

**Norway:** Load is  $120\Omega$  in series with a parallel combination of  $820\Omega$  and 110nF. This is synthesized on the MH88632 by  $1.5k\Omega$  in series with a parallel combination of 12nF and  $7.8k\Omega$ .

*Italy:* Load is 750 $\Omega$  in parallel with 18nF. This is synthesised on the MH88632 by 1.5k $\Omega$  in series with a parallel combination of 2nF and 6k $\Omega$ .

### **Network Balance**

Transhybrid loss is maximized when the line termination impedance and COIC network balance are matched. The MH88632's network balance impedance can be set to Z\_in, AT&T (350 $\Omega\text{+}1k\Omega$  // 210nf) or to a user Selectable value. Thus, the network balance impedance can be set to any international requirement. A logic level control input NS selects the balance mode. With NS at logic low, an internal network balance impedance is matched to the line impedance (Z<sub>in</sub>). With NS at logic high, a user defined network balance impedance is selected which is 0.1 times the impedance between N1 and AGND. For example, with  $2200\Omega$  in series with 11.5nF in parallel with 8200Ω, all between N1and AGND, and NS at logic high, the devices network balance impedance in  $220\Omega$  in series with 115nF in parallel with 820 $\Omega$ , the impedance between N1 and N2 must be equivalent to 10 times the input impedance (Z<sub>in</sub>). In addition, with NS at logic high, an AT&T network balance impedance can be selected by connecting NATT to N1; in this case, no additional network is required between N1 and N2. See Table 4 and Figures 6 & 7.

# **TIP-RING Drive Circuit**

The audio input ground referenced signal at RX is converted to a balanced output signal at Tip and Ring. The Tip-Ring Drive Circuit is optimised for good 2-Wire longitudinal balance.

## **TIP-RING Receive Circuit**

The differential audio signal at Tip and Ring is converted to a ground referenced audio signal at the TX output. This circuit operates with or without loop current; signal reception with no loop current is required for on-hook reception enabling the detection of ANI (Automatic Number Identification) signals.

# Programmable Transmit and Receive Gain

Transmit gain (Tip-Ring to TX) and receive Gain (RX to Tip-Ring) are programmed by connecting external resistors (RRX and RTX) from GRX1 to AGND and from GTX1 to AGND as indicated in Figure 3 and Tables 1 and 2. The programmable gain range is from -12dB to +6dB; this wide range will accommodate any loss plan. Alternatively, the default Receive Gain of 0dB and Transmit Gain of 0dB can be obtained by connecting GRX0 to GRX1 and GTX0 to GTX1. In addition, a Receive Gain of +6dB and Transmit Gain of +6dB can be obtained by not connecting resistors RRX and RTX. For correct gain programming, the MH88632's Tip-Ring impedance (Z<sub>in</sub>) must match the line termination impedance. For optimum performance, resistor RRX should be physically located as close as possible to the GRX1 input pin.

# ANI (Automatic Number Identification)

ANI provides the called party with calling party telephone number identification. The central office utilizes the voice path of a regular loop-start telephone line when the COIC (subscriber's terminal) is in the on-hook state. The central office sends the ANI information (data transmission typically of an FSK signal of 1200Hz and 2200Hz) typically 600ms after the first ringing burst.

The COIC outputs this FSK signal at the TX output.

#### **Absolute Maximum Ratings\***

	Parameter	Sym	Min	Max	Units
1	DC Supply Voltage	V <sub>DD</sub>	-0.3	7	V
		V <sub>EE</sub>	0.3	-7	V
2	DC Ring Relay Voltage	V <sub>RLY</sub>	-0.3	20	V
3	Storage Temperature	Τ <sub>S</sub>	-55	+125	°C

\* Exceeding these values may cause permanent damage. Functional operation under these conditions is not implied.

#### **Recommended Operating Conditions**

	Parameter	Sym	Тур*	Min	Max	Units	Comments
1	DC Supply Voltage	V <sub>DD</sub>	5.0	4.75	5.25	V	
		V <sub>EE</sub>	-5.0	-4.75	-5.25	V	
2	DC Ring Relay Voltage	V <sub>VRLY</sub>	5.0		15	V	
3	Operating Temperature	T <sub>OP</sub>		0	70	°C	

\* Typical figures are at  $25^{\circ}$  C with nominal  $\pm$  5V supplies for design aid only.

# DC Electrical Characteristics<sup>†</sup>

		Characteristics	Sym	Min	Тур*	Max	Units	Test Conditions
1		Supply Current	I <sub>DD</sub> I <sub>EE</sub>			13 13	mA mA	
2		Power Consumption	PC			137	mW	
3	FL RL RG TG RV	Low Level Output Voltage High Level Output Voltage	V <sub>OL</sub> V <sub>OH</sub>	2.4		0.5	V V	I <sub>OL</sub> = 4mA I <sub>OH</sub> = 0.5mA
4	LRD BRD GRD	Sink Current, Relay to V <sub>DD</sub> Clamp Diode Current	I <sub>OL</sub> I <sub>CD</sub>	100 510			mA mA	V <sub>OL</sub> =35V
5	NS LRC BRC	Low Level Input Voltage High Level Input Voltage	V <sub>IL</sub> V <sub>IH</sub>	2.0		0.8	V V	
6	GRC	High Level Input Current Low Level Input Current	I <sub>IH</sub> I <sub>IL</sub>		1 1		μΑ μΑ	

# Loop Electrical Characteristics<sup>†</sup>

	Characteristics	Sym	Min	Тур*	Max	Units	Test Conditions
1	Ringing Voltage	VR	40	90	130	Vrms	
2	Ringing Frequency		17	20	33	Hz	
3	Ringer Equivalent Number	REN			3		
	(Туре А)						
4	Operating Loop Current		18			mA	
5	Operating Loop Resistance		0		90	Ω	@18mA, -48V
6	Off-Hook DC Resistance				2300	Ω	
7	Leakage Current (Tip-Ring to AGND)				10	mA	@1000Vac
8	FL Threshold Tip-Ring Voltage Detect Tip-Ring Current Detect		+30 +1.0		+40 +4.2	Vdc Vdc	LRC-0V LRC=0V

# Loop Electrical Characteristics (Continued)

	Characteristics	Sym	Min	Тур*	Max	Units	Test Conditions
9	RL Threshold						
	Tip-Ring Voltage Detect		-30		-40	Vdc	LRC = 0v
	Tip-Ring Current Detect		-1.0		-40	Vdc	LRC = 0V
10	TG and RG Detect Threshold		-12		-14	Vdc	

DC Electrical Characteristics are over recommended operating conditions unless otherwise stated.
 Typical figures are at 25°C with nominal ±5V supplies and are for design aid only.
 AC Electrical Characteristics<sup>†</sup>

	Characteristics	Sym	Min	Тур*	Max	Units	Test Conditions
1	2-wire Input Impedance ①	Z <sub>in</sub>		600 900		Ω Ω	
				Ext.		Ω	
2	Return Loss at 2-Wire	RL	20			dB	200-500 Hz
	$(Z_{in} = \text{Ref.} = 600\Omega)$		20 20			dB dB	500-1000 Hz 1000-3400 Hz
3	Return Loss at 2-Wire	RL	20			dB	200-500 Hz
J	$(Z_{in} = \text{Ref.} = 900\Omega)$		20			dB	500-1000 Hz
	( III )		20			dB	1000-3400 Hz
4	Return Loss at 2-Wire 2	RL	20			dB	200-500 Hz
	(Z <sub>in</sub> = Ref. = External)		20			dB	500-1000 Hz
5	Leonitudio el te Matellia Delence		20			dB	1000-3400 Hz
5	Longitudinal to Metallic Balance (2) ③ ④		58 58			dB dB	200 Hz 1000 Hz
			55			dB	2000 Hz
			53			dB	3000 Hz
			51			dB	4000 Hz
6	Metallic to Longitudinal Balance		60			dB	200-1000 Hz
	The set of the set		40			dB	1000 -4000 Hz
7	Transhybrid Loss ( $Z_{in} = Ref. = Net = 600\Omega$ )	THL	18 21			dB dB	200-3400 Hz 500-2500 Hz
8	Transhybrid Loss	THL	18			dB	200-3400 Hz
Ŭ	$(Z_{in} = \text{Ref.} = \text{Net} = 900\Omega)$		21			dB	500 -2500 Hz
9	Transhybrid Loss	THL	18			dB	200-3400 Hz
	(Z <sub>in</sub> = Ref. = Net = External)		21			dB	500-2500 Hz
10	Transhybrid Loss	THL	18			dB	200-3400 Hz
11	$(Z_{in} = \text{Ref.} = \text{Net} = 600\Omega)$		21			dΒ kΩ	500-2500 Hz
12	Input Impedance At RX Output Impedance at TX					κ <u>ι</u> 2	
12	Transmit Gain, (TX/2-Wire):					52	Input 0.5V
15	Default Gain (0dB) ② ③					dB	1kHz
	Programmable Range					dB	1kHz
	Frequency response gain ② ③					dB	200 Hz
	(relative to gain at 1kHz)					dB	300 Hz
						dB	3000 Hz
						dB	3400 Hz
14	Receive Gain, (2-Wire/RX):					d۵	Input 0.5V 1kHz
1	Default Gain (0dB) ② ③ Programmable Range					dB dB	1kHz
	Frequency response gain ② ③					dB	200 Hz
	(relative to gain at 1kHz)					dB	300 Hz
						dB	3000 Hz
						dB	3400 Hz

# AC Electrical Characteristics<sup>†</sup> (Continued)

	Characteristics	Sym	Min	Тур*	Max	Units	Test Conditions
15	Signal Output Overload Level at 2-wire at TX		4.0 4.0			dBm dBm	% THD< 5% Ref. 600Ω Ref. 600Ω
16	Total Harmonic Distortion at 2-Wire at TX	THD		1.0 1.0		% %	Input 0.5V, 1kHz
17	Idle Channel Noise at 2-Wire at Tx	Nc			13 13	dBrnC dBrnC	
18	Power Supply Rejection Ratio at 2-Wire and TX $V_{DD}$ $V_{EE}$	PSRR	20 20	30 30		dB dB	Ripple 0.1V, 1kHz
19	On-Hook Transmit Gain, (TX/2-Wire) Default Gain (0dB Programmable Range On-Hook frequency Response Gain (relative to gain to 1kHz)		-1 -12 -3 -1		1 6 1	dB dB dB dB	Input 0.5V 1kHz 1kHz 200 Hz 3400 Hz

Typical figure are at 25°C with nominal ±5V supplies and are for design aid only.
 † AC Electrical Characteristics are over recommended operating conditions unless otherwise stated.
 ①Impedance set by external network of 600Ω or 900Ω default.

@External network for test purposes consists of 2200 $\Omega$  + 8200 $\Omega$  // 11.5nF between pins Z1 and Z2, the equivalent Zin has 1/10<sup>th</sup> the impedance and is equivalent o  $220\Omega + 820\Omega$  // 115nF

3Test condition uses a Z<sub>in</sub> value of 600Ω, 900Ω and the above external network.

Test conditions use a transmit and receive gain set to 0dB default and a Z<sub>in</sub> value of 600Ω unless otherwise stated. Notes:

Test conditions use a transmit and receive gain set to 0dB default and a Z<sub>in</sub> value of 600W unless otherwise stated.

Test conditions uses both the off-hook state (LRC=+5VDC) and the on-hook state (LRC=AGND)

"Ref" indicates reference impedance which is equivalent to the termination impedance.

"Net" indicates network balance impedance

#### Tables 1 & 2: Transmit and Receive Gain Programming

Transmit Gain (dB)	RTX Resistor Value (Ω)	Notes
+6.0	No Resistor	
+4.0	38.3k	Results in 0dB overall gain when used with Mitel A-law codec (i.e. MT8965)
+3.7	32.4k	Results in 0dB overall gain when used with Mitel $\mu$ -law codec (i.e. MT8964)
0.0	GTX0 to GTX1	
-3.0	5.49k	
-6.0	3.32k	
-12.0	1.43k	
Receive Gain (dB)	RRX Resistor Value (Ω)	Notes
		Notes
(dB)	Value (Ω)	Notes
(dB) +6.0	Value (Ω) No Resistor	Notes
(dB) +6.0 0.0	Value (Ω) No Resistor GRX0 to GRX1	Notes Notes Results in 0dB overall gain when used with Mitel A-law codec (i.e. MT8965)
(dB) +6.0 0.0 -3.0	Value (Ω) No Resistor GRX0 to GRX1 5.49k	
(dB) +6.0 0.0 -3.0 -3.7	Value (Ω) No Resistor GRX0 to GRX1 5.49k 4.87k	Results in 0dB overall gain when used with Mitel A-law codec (i.e. MT8965)

Note 1: See Figures 3 and 4 for additional details.

Note 2: Overall gain refers to the receive path of PCM to 2-wire, and transmit path of 2-wire to PCM.

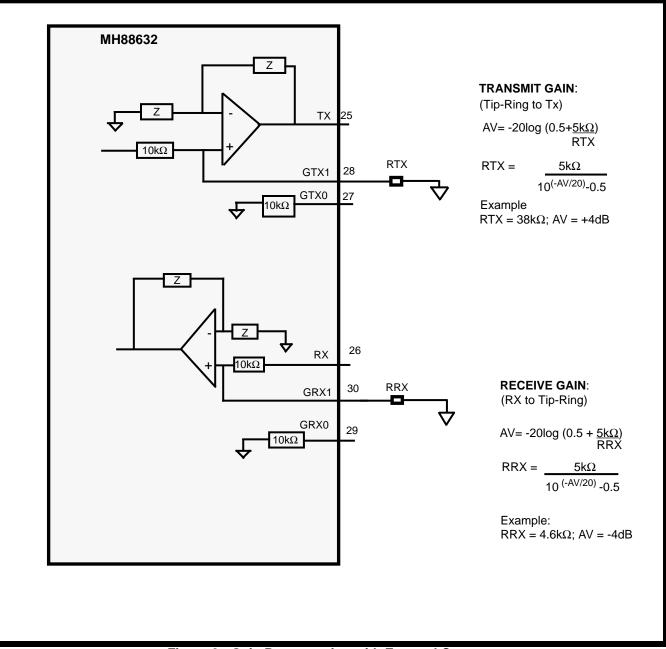
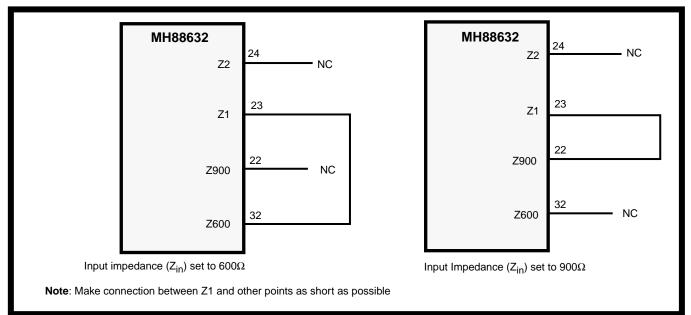
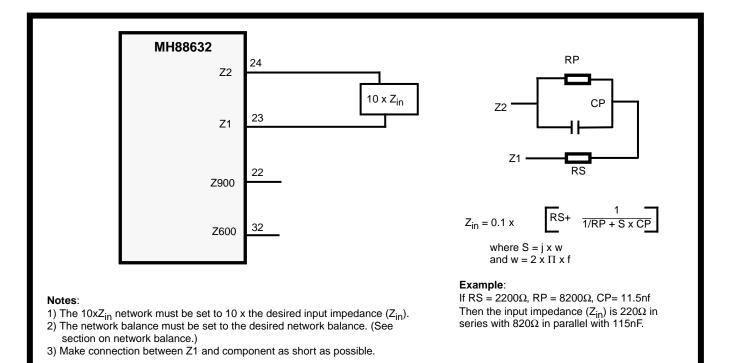


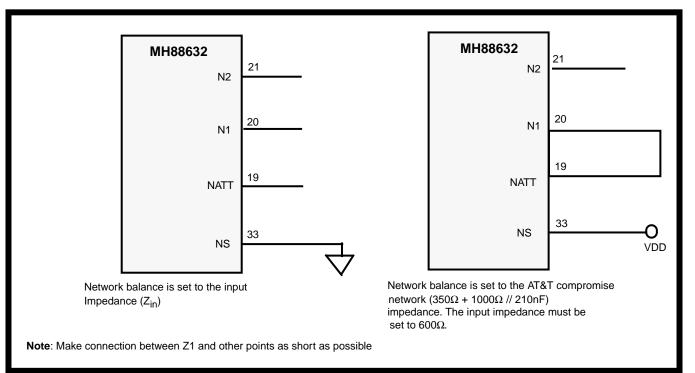
Figure 3 - Gain Programming with External Components

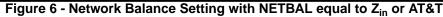


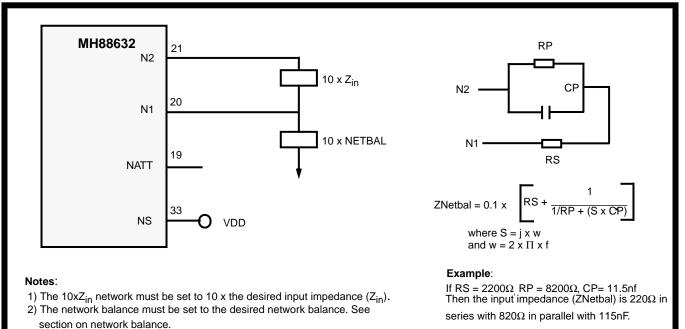












3) Make connection between Z1 and component as short as possible.

Figure 7 - Network Balance Setting with NETBAL not equal to Z<sub>in</sub> or AT&T

#### Table 3: Input Impedance Settings

Z2	Z1	Z600	Z900	Resulting input impedance (Z <sub>in</sub> )
NA	Connect Z1 to Z600		NA	600Ω
NA	Connect Z1 to Z9000	NA	Connect Z1 to Z900	900Ω
Connect netwo	rk from Z1 to Z2	NA	NA	0.1 x impedance between Z1 & Z2

Note 1: NA indicates high impedance  $(10k\Omega)$  connection to this pin does not effect the resulting network balance. Note 2: See Figure 4 & 5 for Applications Circuits

#### Table 4: Network Balance Settings.

NS (Input)	N2	N1	NATT	Resulting input impedance (Z <sub>in</sub> )	
Low	NA	NA	NA	Equivalent to Z <sub>in</sub>	
High	NA	Connect N1 to NATT		AT&T compromise $(350\Omega + 1k\Omega // 210nF)$ Zin must be $600\Omega$	
High	Connect network from N1 to AGND equivalent to 10 x NETBAL. Connect network from N1 to N2 equivalent to 10 x Z <sub>in</sub> .		NA	0.1 x impedance between N1 & N2	

Note 1: NA indicates high impedance  $(10k\Omega)$  connection to this pin does not effect the resulting network balance.

Note 2:Low indicates Logic Low.

Note 3: See Figures 6 and 7 for Application Circuit.

Loop Status	Loop Condition	LRC (Input)	FL (Output)	RL (Output)
Forward Battery	VT-VR > 40 V	Low	Low	High
Forward Current	VT-VR > 3.4 V	High	Low	High
Reverse Battery	VR-VT > 40V	Low	High	Low
Forward Current	VR-VT > 3.4 V	High	High	Low
No Battery	IVT-VRI > 1.0 V	Low	High	High
No Current	IVT-VRI > 10 V	High	High	High
Not Valid	No Condition	High or Low	Low	Low

#### **Table 5: Control Decode Table**

Note 1: VT - VR = Differential voltage from Tip to Ring VR - VT = Differential voltage from Ring to Tip

Note 2: Low indicates Logic Low. High indicates logic High.

Note 3: See Figures 8 & 10 for Application Circuit.

#### **Table 6: Loop Current Setting**

Loop Status	Loop Condition	RG (Output)	TG (Output)
Ring and Tip open	VT-VG > -14 V VR-VG < -14V	High	High
Ring Ground and Tip Open	VR-VG > -12 V VT-VG < -14V	Low	High
Tip Ground and Ring Open	VT-VG > -12 V VR-VG < -14V	High	Low
Ring and Tip Ground	VR-VG > -12 V VT-VG < -12V	Low	Low

Note 1: VT - VR = Differential voltage from Tip to Ring VR - VT = Differential voltage from Ring to AGND

Note 2: A > -B indicates that "A" is less negative than "-B". A<-B indicates that "A" is more negative than "-B".

Note 3:Low indicates Logic Low. High indicates logic High.

Note 4: See Figure 8 for Application Circuit.

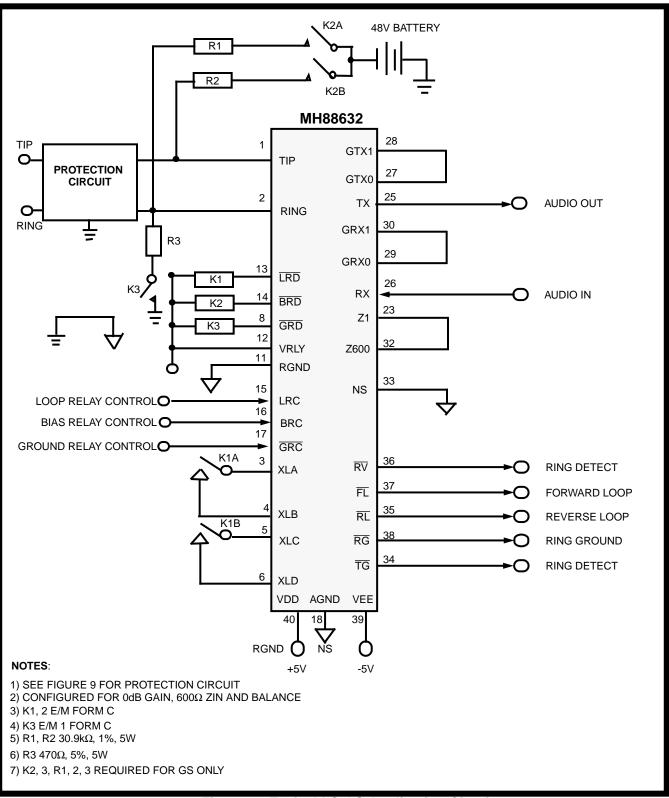


Figure 8 - Typical LS-GS Application Circuit

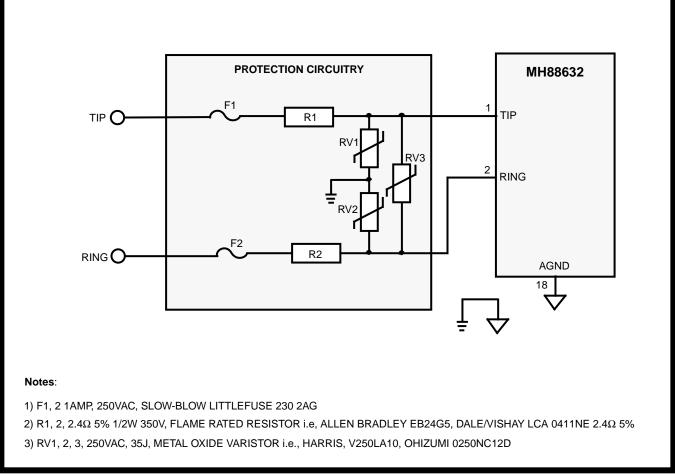


Figure 9 - External Protection Applications Circuit

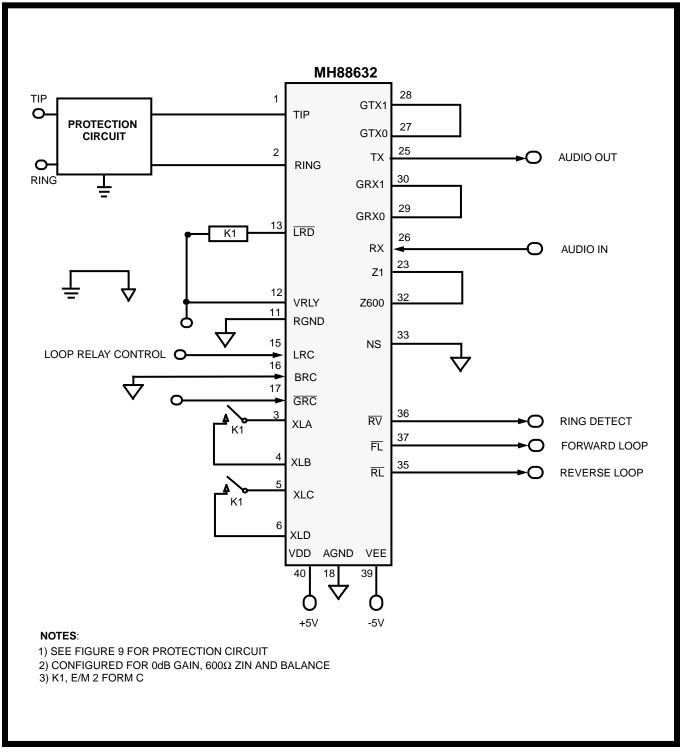


Figure 10 - Typical LS Application Circuit

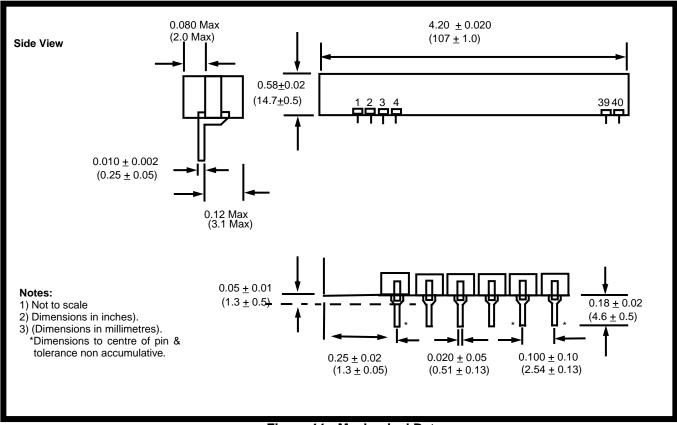


Figure 11 - Mechanical Data